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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

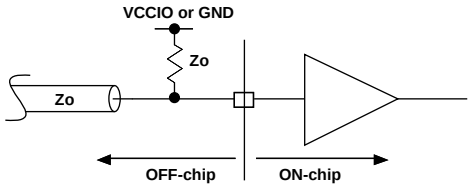
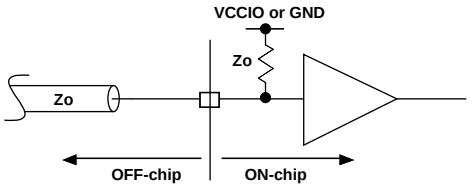
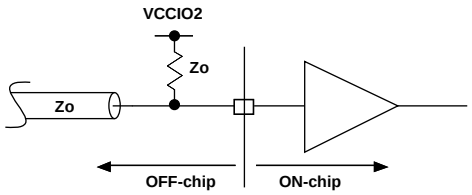
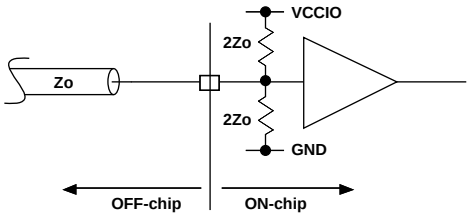
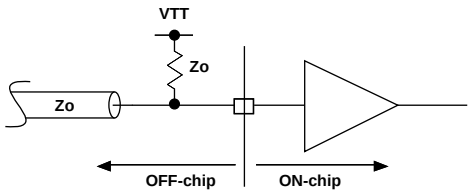
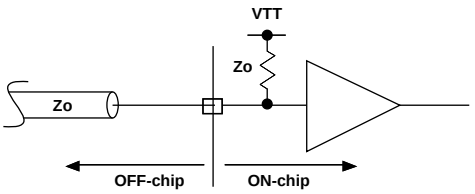
Details	
Product Status	Obsolete
Number of LABs/CLBs	28750
Number of Logic Elements/Cells	115000
Total RAM Bits	7987200
Number of I/O	660
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga115ep1-5fcn1152c

Single Ended Inputs: The SC devices support a number of different termination schemes for single ended inputs:

- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to V_{TT}

Figure 2-28 shows the single ended input schemes that are supported. The nominal values of the termination resistors are shown in Table 2-9.

Figure 2-28. Input Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Parallel termination to to V_{CCIO}, or parallel to GND receiving end		
Parallel termination to $V_{CCIO}/2$ receiving end		
Parallel termination to V_{TT} at receiving end		

In many situations designers can chose whether to use Thevenin or parallel to V_{TT} termination. The Thevenin approach has the benefit of not requiring a termination voltage to be applied to the device. The parallel to V_{TT} approach consumes less power.

VTT Termination Resources

Each I/O bank, except bank 1, has a number of V_{TT} pins that must be connected if V_{TT} is used. Note V_{TT} pins can sink or source current and the power supply they are connected to must be able to handle the relatively high currents associated with the termination circuits. Note: V_{TT} is not available in all package styles.

On-chip parallel termination to V_{TT} is supported at the receiving end only. On-chip parallel output termination to V_{TT} is not supported.

The V_{TT} internal bus is also connected to the internal V_{CMT} node. Thus in one bank designers can implement either V_{TT} termination or V_{CMT} termination for differential inputs.

DDRII/RLDRAMII Termination Support

The DDR II memory and RLDRAMII (in Bidirection Data mode) standards require that the on-chip termination to V_{TT} be turned on when a pin is an input and off when the pin is an output. The LatticeSC devices contain the required circuitry to support this behavior. For additional detail refer to technical information at the end of the data sheet.

LatticeSC/M Family Timing Adders

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Input Adjusters								
LVDS	LVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
RSDS	RSDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
BLVDS25	BLVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
MLVDS25	MLVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
LVPECL33	LVPECL	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
HSTL18_I	HSTL_18 class I	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL18_II	HSTL_18 class II	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL18_III	HSTL_18 class III	-0.016	-0.018	0.008	0.003	0.032	0.023	ns
HSTL18_IV	HSTL_18 class IV	-0.016	-0.018	0.008	0.003	0.032	0.023	ns
HSTL18D_I	Differential HSTL 18 class I	0.006	0.001	0.029	0.024	0.052	0.046	ns
HSTL18D_II	Differential HSTL 18 class II	0.006	0.001	0.029	0.024	0.052	0.046	ns
HSTL15_I	HSTL_15 class I	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
HSTL15_II	HSTL_15 class II	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
HSTL15_III	HSTL_15 class III	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL15_IV	HSTL_15 class IV	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL15D_I	Differential HSTL 15 class I	-0.021	-0.022	0.001	-0.009	0.022	0.003	ns
HSTL15D_II	Differential HSTL 15 class II	-0.021	-0.022	0.001	-0.009	0.022	0.003	ns
SSTL33_I	SSTL_3 class I	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns
SSTL33_II	SSTL_3 class II	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns
SSTL33D_I	Differential SSTL_3 class I	0.012	0.012	0.034	0.028	0.055	0.043	ns
SSTL33D_II	Differential SSTL_3 class II	0.012	0.012	0.034	0.028	0.055	0.043	ns
SSTL25_I	SSTL_2 class I	0.003	-0.008	0.03	0.011	0.058	0.03	ns
SSTL25_II	SSTL_2 class II	0.003	-0.008	0.03	0.011	0.058	0.03	ns
SSTL25D_I	Differential SSTL_2 class I	0.006	0	0.031	0.023	0.056	0.046	ns
SSTL25D_II	Differential SSTL_2 class II	0.006	0	0.031	0.023	0.056	0.046	ns
SSTL18_I	SSTL_18 class I	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
SSTL18_II	SSTL_18 class II	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
SSTL18D_I	Differential SSTL_18 class I	0.006	0.001	0.029	0.024	0.052	0.046	ns
SSTL18D_II	Differential SSTL_18 class II	0.006	0.001	0.029	0.024	0.052	0.046	ns
LVTTL33	LVTTL	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
LVCMOS33	LVCMOS 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
LVCMOS25	LVCMOS 2.5	0	0	0	0	0	0	ns
LVCMOS18	LVCMOS 1.8	-0.068	-0.068	-0.087	-0.087	-0.105	-0.105	ns
LVCMOS15	LVCMOS 1.5	-0.131	-0.131	-0.186	-0.186	-0.241	-0.241	ns
LVCMOS12	LVCMOS 1.2	-0.238	-0.238	-0.364	-0.364	-0.49	-0.49	ns
PCI33	PCI	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
PCIX33	PCI-X 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
PCIX15	PCI-X 1.5	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
AGP1X33	AGP-1X 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
AGP2X33	AGP-2X	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns

LatticeSC/M Family Timing Adders (Continued)

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.024	-0.106	0.019	-0.004	0.016	0.099	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.074	-0.134	0.08	-0.022	0.088	0.089	ns
LVCMOS18_OD	LVCMOS 1.8 open drain	0.002	-0.206	0	-0.196	-0.002	-0.221	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	-0.344	-0.164	-0.379	-0.186	-0.412	-0.209	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	-0.125	-0.137	-0.145	-0.157	-0.164	-0.176	ns
LVCMOS15_12mA	LVCMOS 1.5 12mA drive	-0.027	-0.166	-0.043	-0.07	-0.059	0.026	ns
LVCMOS15_16mA	LVCMOS 1.5 16mA drive	0.025	-0.195	0.013	-0.089	0.003	0.017	ns
LVCMOS15_OD	LVCMOS 1.5 open drain	-0.047	-0.267	-0.067	-0.267	-0.087	-0.299	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	-0.473	-0.293	-0.505	-0.317	-0.537	-0.34	ns
LVCMOS12_4mA	LVCMOS 1.2 4mA drive	-0.218	-0.239	-0.25	-0.271	-0.28	-0.303	ns
LVCMOS12_8mA	LVCMOS 1.2 8mA drive	-0.109	-0.269	-0.143	-0.181	-0.176	-0.093	ns
LVCMOS12_12mA	LVCMOS 1.2 12mA drive	-0.054	-0.3	-0.085	-0.203	-0.114	-0.106	ns
LVCMOS12_OD	LVCMOS 1.2 open drain	-0.126	-0.371	-0.166	-0.398	-0.204	-0.43	ns
PCI33	PCI	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
PCIX33	PCI-X 3.3	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
PCIX15	PCI-X 1.5	0.208	0.227	0.233	0.312	0.259	0.398	ns
AGP1X33	AGP-1X 3.3	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
AGP2X33	AGP-2X	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns

Input Delay Block/AIL Timing

Parameter	Description	Min.	Typ.	Max.	Units
t_{FDEL}	Fine delay time	35	45	80	ps
t_{CDEL}	Coarse delay time	1120	1440	2560	ps
jt_{AIL}	AIL jitter tolerance	1- ((N^1 * t_{FDEL}) / (Clock Period))			UI

1. N = number of fine delays used in a particular AIL setting

GSR Timing

Parameter	Description	VCC	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
$t_{SYNC\_GSR\_MAX}$	Maximum operating frequency for synchronous GSR	1.14V	—	438	—	417	—	398	MHz
		0.95V	—	378	—	355	—	337	MHz
$t_{ASYNC\_GSR\_MPW}$	Minimum pulse width of asynchronous input	—	—	—	—	—	3.3	—	ns

Note: Synchronous GSR goes out of reset in two cycles from the clock edge where the setup time of the FF was met.

Internal System Bus Timing

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{HCLK}	Maximum operating frequency for internal system bus HCLK.	—	200	—	200	—	200	MHz

Note: There is no minimum frequency. If HCLK is sourced from the embedded oscillator, the minimum frequency limitation of the oscillator/ divider is about 0.3 MHz. Refer to the osciallator data for missing configuration modes.

Switching Test Conditions

Figure 3-15 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-4.

Figure 3-15. Output Test Load, LVTTL and LVCMOS Standards

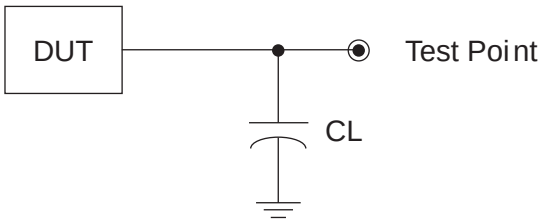


Table 3-4. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	30pF	LVCMOS 3.3 = 1.5V	—
		LVCMOS 2.5 = $V_{CCIO}/2$	—
		LVCMOS 1.8 = $V_{CCIO}/2$	—
		LVCMOS 1.5 = $V_{CCIO}/2$	—
		LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	30pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)		$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)		V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)		V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
PROBE_GND	—	GND signal - Connected to internal VSS node. Can be used for feedback to control an external board power converter. Can be unconnected if not used.
PLL and Clock Functions (Used as user-programmable I/O pins when not in use for PLL, DLL or clock pins.)		
[LOC]_PLL[T, C]_FB_[A/B]	I	PLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T, C] indicates whether input is true or complement. [A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_FB_[C, D, E, F]	I	DLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners.
[LOC]_PLL[T, C]_IN[A/B]	I	PLL reference clock input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T, C] indicates whether input is true or complement.[A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_IN[C, D, E, F]		DLL reference clock inputs. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners. PCKLxy_[0:3] can drive primary clocks, edge clocks, and CLKDIVs. PCLKxy_[4:7] can only drive edge clocks.
PCLKxy_z		General clock inputs. x indicates whether T (true) or C (complement). y indicates the I/O bank the clock is associated with. z indicates the clock number within a bank.
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
Configuration Pads (Dedicated pins. Used during sysCONFIG.)		
M[3:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled that will pull the I/O above 1.5V.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESETN		Reset. (Also sent to general routing). During configuration it resets the configuration state machine. After configuration this pin can perform the global set/reset (GSR) functions or can be used as a general input pin.
CFGIRQN	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
TSALLN	I	Tristates all I/O.
Configuration Pads (User I/O if not used. Used during sysCONFIG.)		
HDC/SI	O	High During Configuration is output high until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this pin is used to download the read command and initial read address into the Flash memory device on the falling edge of SCK. This pin will be connected to SI of the memory. If the SPI mode is used, the 8-bit instruction code 0x03 will be downloaded followed by a 24-bit starting address of 0x000000 or a non-zero stat address for partial reconfiguration. If the SPIX mode has been selected, the 8-bit instruction captured on D[7:0] at power-up will be shifted in and followed by a 32-bit starting address of 0x000000.
LDCN/SCS	O	Low During Configuration is output low until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this is an active low chip select for Flash memories. It will go active after INITN goes high but before SCK begins. During power up LDCN will be low. Once INITN goes high, LDCN will go high for 100ns-200ns after which time it will go back low and configuration can begin. During the 100ns-200ns period, the read instruction will be latched for SPIX mode.
DOUT	O	Serial data output that can drive the D0/DIN of daisy-chained slave devices. The data-stream from this output will propagate preamble bits of the bitstream to daisy-chained devices. Data out on DOUT changes on the rising edge of CCLK.
QOUT/CEON	O	During daisy-chaining configuration, QOUT is the serial data output that can drive the D0/DIN of daisy-chained slave devices that do not propagate preamble bits. Data out on QOUT changes on the rising edge of CCLK. During parallel-chaining configuration, active low CEON enables the cascaded slave device to receive bitstream data.
RDN	I	Used in the asynchronous peripheral configuration mode. A low on RDN changes D[7:3] into status outputs. WRN and RDN should not be used simultaneously. If they are, the write strobe overrides.
WRN	I	When the FPGA is selected, a low on the write strobe, WRN, loads the data on D[7:0] inputs into an internal data buffer.
CS0N CS1	I	Used in the asynchronous peripheral, slave parallel and MPI modes. The FPGA is selected when CS0N is low and CS1 is high. During configuration, a pull-up is enabled on both except with MPI DMA access control.
A[21:0]	I/O	In master parallel mode, A[21:0] is an output and will address the configuration EPROMs up to 4 MB space. For MPI configuration mode, A[17:0] will be the MPI address MPI_ADDR[31:14], A[19:18] will be the transfer size and A[21:20] will be the burst mode and burst in process.

Pin Information Summary

Pin Type		256 fpBGA	900 fpBGA		1020 fcBGA	
		LFSC/M15	LFSC/M15	LFSC/M25	LFSC/M25	LFSC/M40
Single Ended User I/O		139	300	378	476	562
Differential Pair User I/O		60	141	182	235	277
LVDS Output Pairs		22	44	60	60	78
Configuration	Dedicated	9	11	11	11	11
	Muxes/MPI sysBus	0	55	55	55	72
JTAG (excluding VCCJ)		4	4	4	4	4
Dedicated Pins		2	4	4	4	4
VCC		10	46	46	40	40
VCC12		10	35	35	36	36
VCCAUX		10	36	36	32	32
VCCIO	Bank 1	3	18	18	10	10
	Bank 2	2	14	14	8	8
	Bank 3	2	15	15	10	10
	Bank 4	3	15	15	10	10
	Bank 5	3	15	15	10	10
	Bank 6	2	15	15	10	10
	Bank 7	2	16	16	8	8
VTT	Bank 2	0	2	2	2	2
	Bank 3	0	3	3	3	3
	Bank 4	0	3	3	3	3
	Bank 5	0	3	3	3	3
	Bank 6	0	3	3	3	3
	Bank 7	0	2	2	2	2
GND		26	177	177	134	134
NC		0	102	24	92	6
Single Ended User / Differential I/O per Bank	Bank 1	21/8	63/30	63/30	68/32	68/32
	Bank 2	15/7	26/13	30/15	34/17	54/27
	Bank 3	19/8	43/20	62/29	84/42	94/47
	Bank 4	25/11	50/22	66/32	84/41	99/48
	Bank 5	25/11	49/23	65/32	88/44	99/49
	Bank 6	19/8	43/20	62/29	84/42	94/47
	Bank 7	15/7	26/13	30/15	34/17	54/27
LVDS Output Pairs Per Bank	Bank 2	5	7	9	9	15
	Bank 3	6	15	21	21	24
	Bank 6	6	15	21	21	24
	Bank 7	5	7	9	9	15
VCCJ		1	1	1	1	1
SERDES (signal + power supply)		28	60	60	108	108
Total		256	900	900	1020	1152

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
C5	A_VDDIB1_L	-	
A5	A_HDINP1_L	-	PCS 360 CH 1 IN P
B5	A_HDINN1_L	-	PCS 360 CH 1 IN N
A4	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
B4	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
C4	A_VDDOB1_L	-	
B3	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
C3	A_VDDOB0_L	-	
A3	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
B2	A_HDINN0_L	-	PCS 360 CH 0 IN N
A2	A_HDINP0_L	-	PCS 360 CH 0 IN P
C2	A_VDDIB0_L	-	
A1	GND	-	
A16	GND	-	
B10	GND	-	
C13	GND	-	
D15	GND	-	
D3	GND	-	
E11	GND	-	
F13	GND	-	
G14	GND	-	
G2	GND	-	
G8	GND	-	
H10	GND	-	
J7	GND	-	
K15	GND	-	
K3	GND	-	
K9	GND	-	
M6	GND	-	
N11	GND	-	
N14	GND	-	
N2	GND	-	
P10	GND	-	
P4	GND	-	
R13	GND	-	
R7	GND	-	
G10	VCC	-	
G7	VCC	-	
G9	VCC	-	
H7	VCC	-	
H8	VCC	-	
H9	VCC	-	
J10	VCC	-	
J8	VCC	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y6	PR42D	3	DIFFR_3	PR51D	3	DIFFR_3
W6	PR42C	3		PR51C	3	
Y2	PR42B	3		PR51B	3	
W2	PR42A	3		PR51A	3	
W7	PR40D	3		PR49D	3	
V8	PR40C	3		PR49C	3	
W4	PR40B	3		PR49B	3	
W3	PR40A	3		PR49A	3	
V5	PR39D	3		PR48D	3	
U6	PR39C	3		PR48C	3	
V3	PR39B	3		PR48B	3	
V4	PR39A	3		PR48A	3	
V10	PR38D	3		PR47D	3	
V9	PR38C	3		PR47C	3	
V2	PR38B	3		PR47B	3	
V1	PR38A	3		PR47A	3	
U8	PR36D	3		PR45D	3	
U7	PR36C	3		PR45C	3	
U2	PR36B	3		PR45B	3	
U1	PR36A	3		PR45A	3	
U5	PR35D	3		PR44D	3	
T6	PR35C	3		PR44C	3	
T1	PR35B	3		PR44B	3	
T2	PR35A	3		PR44A	3	
U9	PR34D	3		PR43D	3	
U10	PR34C	3	VREF1_3	PR43C	3	VREF1_3
R1	PR34B	3		PR43B	3	
R2	PR34A	3		PR43A	3	
T7	PR31D	3	PCLKC3_2	PR40D	3	PCLKC3_2
T8	PR31C	3	PCLKT3_2	PR40C	3	PCLKT3_2
R4	PR31B	3		PR40B	3	
R3	PR31A	3		PR40A	3	
T5	PR30D	3	PCLKC3_3	PR39D	3	PCLKC3_3
R5	PR30C	3	PCLKT3_3	PR39C	3	PCLKT3_3
P2	PR30B	3		PR39B	3	
P1	PR30A	3		PR39A	3	
T9	PR29D	3	PCLKC3_1	PR38D	3	PCLKC3_1
T10	PR29C	3	PCLKT3_1	PR38C	3	PCLKT3_1
P4	PR29B	3	PCLKC3_0	PR38B	3	PCLKC3_0
P3	PR29A	3	PCLKT3_0	PR38A	3	PCLKT3_0
P5	PR27D	2	PCLKC2_2	PR36D	2	PCLKC2_2
P6	PR27C	2	PCLKT2_2	PR36C	2	PCLKT2_2
N1	PR27B	2	PCLKC2_0	PR36B	2	PCLKC2_0
N2	PR27A	2	PCLKT2_0	PR36A	2	PCLKT2_0
R9	PR26D	2	PCLKC2_3	PR35D	2	PCLKC2_3
R8	PR26C	2	PCLKT2_3	PR35C	2	PCLKT2_3
M1	PR26B	2	PCLKC2_1	PR35B	2	PCLKC2_1
L1	PR26A	2	PCLKT2_1	PR35A	2	PCLKT2_1
N9	PR25D	2	DIFFR_2	PR23D	2	DIFFR_2
M9	PR25C	2	VREF1_2	PR23C	2	VREF1_2

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B1	GND	-		GND	-	
B32	GND	-		GND	-	
C11	GND	-		GND	-	
C12	GND	-		GND	-	
C16	GND	-		GND	-	
C21	GND	-		GND	-	
C22	GND	-		GND	-	
C24	GND	-		GND	-	
C25	GND	-		GND	-	
C26	GND	-		GND	-	
C27	GND	-		GND	-	
C29	GND	-		GND	-	
C3	GND	-		GND	-	
C30	GND	-		GND	-	
C4	GND	-		GND	-	
C6	GND	-		GND	-	
C7	GND	-		GND	-	
C8	GND	-		GND	-	
C9	GND	-		GND	-	
D17	GND	-		GND	-	
F18	GND	-		GND	-	
F3	GND	-		GND	-	
F30	GND	-		GND	-	
F9	GND	-		GND	-	
G15	GND	-		GND	-	
G24	GND	-		GND	-	
G29	GND	-		GND	-	
G3	GND	-		GND	-	
J14	GND	-		GND	-	
J22	GND	-		GND	-	
J26	GND	-		GND	-	
J6	GND	-		GND	-	
K11	GND	-		GND	-	
K19	GND	-		GND	-	
K30	GND	-		GND	-	
K4	GND	-		GND	-	
L23	GND	-		GND	-	
L9	GND	-		GND	-	
M13	GND	-		GND	-	
M15	GND	-		GND	-	
M18	GND	-		GND	-	
M20	GND	-		GND	-	
M27	GND	-		GND	-	
M7	GND	-		GND	-	
N12	GND	-		GND	-	
N14	GND	-		GND	-	
N19	GND	-		GND	-	
N21	GND	-		GND	-	
N29	GND	-		GND	-	
N3	GND	-		GND	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AA7	VCCIO3	-		VCCIO3	-	
AB9	VCCIO3	-		VCCIO3	-	
AC4	VCCIO3	-		VCCIO3	-	
AD6	VCCIO3	-		VCCIO3	-	
AF3	VCCIO3	-		VCCIO3	-	
T3	VCCIO3	-		VCCIO3	-	
U4	VCCIO3	-		VCCIO3	-	
V6	VCCIO3	-		VCCIO3	-	
W10	VCCIO3	-		VCCIO3	-	
Y3	VCCIO3	-		VCCIO3	-	
AC11	VCCIO4	-		VCCIO4	-	
AD14	VCCIO4	-		VCCIO4	-	
AF15	VCCIO4	-		VCCIO4	-	
AF9	VCCIO4	-		VCCIO4	-	
AG12	VCCIO4	-		VCCIO4	-	
AJ13	VCCIO4	-		VCCIO4	-	
AJ7	VCCIO4	-		VCCIO4	-	
AK10	VCCIO4	-		VCCIO4	-	
AK16	VCCIO4	-		VCCIO4	-	
AK4	VCCIO4	-		VCCIO4	-	
AC19	VCCIO5	-		VCCIO5	-	
AD22	VCCIO5	-		VCCIO5	-	
AF21	VCCIO5	-		VCCIO5	-	
AG18	VCCIO5	-		VCCIO5	-	
AG24	VCCIO5	-		VCCIO5	-	
AJ17	VCCIO5	-		VCCIO5	-	
AJ23	VCCIO5	-		VCCIO5	-	
AJ30	VCCIO5	-		VCCIO5	-	
AK20	VCCIO5	-		VCCIO5	-	
AK26	VCCIO5	-		VCCIO5	-	
AA27	VCCIO6	-		VCCIO6	-	
AB23	VCCIO6	-		VCCIO6	-	
AC30	VCCIO6	-		VCCIO6	-	
AD26	VCCIO6	-		VCCIO6	-	
AF29	VCCIO6	-		VCCIO6	-	
T29	VCCIO6	-		VCCIO6	-	
U30	VCCIO6	-		VCCIO6	-	
V26	VCCIO6	-		VCCIO6	-	
W24	VCCIO6	-		VCCIO6	-	
Y29	VCCIO6	-		VCCIO6	-	
G30	VCCIO7	-		VCCIO7	-	
J27	VCCIO7	-		VCCIO7	-	
K29	VCCIO7	-		VCCIO7	-	
L24	VCCIO7	-		VCCIO7	-	
M26	VCCIO7	-		VCCIO7	-	
N30	VCCIO7	-		VCCIO7	-	
P23	VCCIO7	-		VCCIO7	-	
R27	VCCIO7	-		VCCIO7	-	
AA11	VCCAUX	-		VCCAUX	-	
AA12	VCCAUX	-		VCCAUX	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
F15	PT55A	1	D5/MPI_DATA5	PT74A	1	D5/MPI_DATA5
K14	PT54D	1	D4/MPI_DATA4	PT73D	1	D4/MPI_DATA4
K13	PT54C	1	D3/MPI_DATA3	PT73C	1	D3/MPI_DATA3
B15	PT53B	1	D2/MPI_DATA2	PT73B	1	D2/MPI_DATA2
A15	PT53A	1	D1/MPI_DATA1	PT73A	1	D1/MPI_DATA1
J14	PT51D	1	D16/PCLKC1_3/MPI_DATA16	PT71D	1	D16/PCLKC1_3/MPI_DATA16
H14	PT51C	1	D17/PCLKT1_3/MPI_DATA17	PT71C	1	D17/PCLKT1_3/MPI_DATA17
A16	PT51B	1	D0/MPI_DATA0	PT71B	1	D0/MPI_DATA0
B16	PT51A	1	QOUT/CEON	PT71A	1	QOUT/CEON
J13	PT50D	1	VREF2_1	PT70D	1	VREF2_1
H13	PT50C	1	D18/MPI_DATA18	PT70C	1	D18/MPI_DATA18
D15	PT50B	1	DOUT	PT70B	1	DOUT
E15	PT50A	1	MCA_DONE_IN	PT70A	1	MCA_DONE_IN
J16	PT49D	1	D19/PCLKC1_2/MPI_DATA19	PT69D	1	D19/PCLKC1_2/MPI_DATA19
J17	PT49C	1	D20/PCLKT1_2/MPI_DATA20	PT69C	1	D20/PCLKT1_2/MPI_DATA20
D16	PT49B	1	MCA_CLK_P1_OUT	PT69B	1	MCA_CLK_P1_OUT
E16	PT49A	1	MCA_CLK_P1_IN	PT69A	1	MCA_CLK_P1_IN
H15	PT47D	1	D21/PCLKC1_1/MPI_DATA21	PT67D	1	D21/PCLKC1_1/MPI_DATA21
H16	PT47C	1	D22/PCLKT1_1/MPI_DATA22	PT67C	1	D22/PCLKT1_1/MPI_DATA22
C15	PT47B	1	MCA_CLK_P2_OUT	PT67B	1	MCA_CLK_P2_OUT
C16	PT47A	1	MCA_CLK_P2_IN	PT67A	1	MCA_CLK_P2_IN
L17	PT46D	1	MCA_DONE_OUT	PT66D	1	MCA_DONE_OUT
K17	PT46C	1	BUSYN/RCLK/SCK	PT66C	1	BUSYN/RCLK/SCK
E17	PT46B	1	DP0/MPI_PAR0	PT66B	1	DP0/MPI_PAR0
F17	PT46A	1	MPI_TA	PT66A	1	MPI_TA
G17	PT45D	1	D23/MPI_DATA23	PT65D	1	D23/MPI_DATA23
H17	PT45C	1	DP2/MPI_PAR2	PT65C	1	DP2/MPI_PAR2
A17	PT45B	1	PCLKC1_0	PT65B	1	PCLKC1_0
B17	PT45A	1	PCLKT1_0/MPI_CLK	PT65A	1	PCLKT1_0/MPI_CLK
G18	PT43D	1	DP3/PCLKC1_4/MPI_PAR3	PT63D	1	DP3/PCLKC1_4/MPI_PAR3
H18	PT43C	1	D24/PCLKT1_4/MPI_DATA24	PT63C	1	D24/PCLKT1_4/MPI_DATA24
E18	PT43B	1	MPI_RETRY	PT63B	1	MPI_RETRY
F18	PT43A	1	A0/MPI_ADDR14	PT63A	1	A0/MPI_ADDR14
J18	PT42D	1	A1/MPI_ADDR15	PT61D	1	A1/MPI_ADDR15
J19	PT42C	1	A2/MPI_ADDR16	PT61C	1	A2/MPI_ADDR16
C20	PT42B	1	A3/MPI_ADDR17	PT61B	1	A3/MPI_ADDR17
C19	PT42A	1	A4/MPI_ADDR18	PT61A	1	A4/MPI_ADDR18
K18	PT41D	1	D25/PCLKC1_5/MPI_DATA25	PT60D	1	D25/PCLKC1_5/MPI_DATA25
L18	PT41C	1	D26/PCLKT1_5/MPI_DATA26	PT60C	1	D26/PCLKT1_5/MPI_DATA26
D19	PT41B	1	A5/MPI_ADDR19	PT60B	1	A5/MPI_ADDR19
E19	PT41A	1	A6/MPI_ADDR20	PT60A	1	A6/MPI_ADDR20
H19	PT39D	1	D27/MPI_DATA27	PT59D	1	D27/MPI_DATA27
H20	PT39C	1	VREF1_1	PT59C	1	VREF1_1
A18	PT39B	1	A7/MPI_ADDR21	PT59B	1	A7/MPI_ADDR21
B18	PT39A	1	A8/MPI_ADDR22	PT59A	1	A8/MPI_ADDR22

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB15	VCC12	-		VCC12	-	
AB20	VCC12	-		VCC12	-	
N15	VCC12	-		VCC12	-	
N20	VCC12	-		VCC12	-	
R13	VCC12	-		VCC12	-	
R22	VCC12	-		VCC12	-	
Y13	VCC12	-		VCC12	-	
Y22	VCC12	-		VCC12	-	
AA12	VCCAUX	-		VCCAUX	-	
AA23	VCCAUX	-		VCCAUX	-	
AB12	VCCAUX	-		VCCAUX	-	
AB16	VCCAUX	-		VCCAUX	-	
AB17	VCCAUX	-		VCCAUX	-	
AB18	VCCAUX	-		VCCAUX	-	
AB19	VCCAUX	-		VCCAUX	-	
AB23	VCCAUX	-		VCCAUX	-	
AC12	VCCAUX	-		VCCAUX	-	
AC13	VCCAUX	-		VCCAUX	-	
Y19	GND	-		GND	-	
AC14	VCCAUX	-		VCCAUX	-	
AC17	VCCAUX	-		VCCAUX	-	
AC21	VCCAUX	-		VCCAUX	-	
AC22	VCCAUX	-		VCCAUX	-	
AC23	VCCAUX	-		VCCAUX	-	
M13	VCCAUX	-		VCCAUX	-	
M14	VCCAUX	-		VCCAUX	-	
M18	VCCAUX	-		VCCAUX	-	
M21	VCCAUX	-		VCCAUX	-	
M22	VCCAUX	-		VCCAUX	-	
N12	VCCAUX	-		VCCAUX	-	
N16	VCCAUX	-		VCCAUX	-	
N17	VCCAUX	-		VCCAUX	-	
N18	VCCAUX	-		VCCAUX	-	
N19	VCCAUX	-		VCCAUX	-	
N23	VCCAUX	-		VCCAUX	-	
P12	VCCAUX	-		VCCAUX	-	
P23	VCCAUX	-		VCCAUX	-	
T13	VCCAUX	-		VCCAUX	-	
T22	VCCAUX	-		VCCAUX	-	
U12	VCCAUX	-		VCCAUX	-	
U13	VCCAUX	-		VCCAUX	-	
U22	VCCAUX	-		VCCAUX	-	
V13	VCCAUX	-		VCCAUX	-	
V22	VCCAUX	-		VCCAUX	-	
V23	VCCAUX	-		VCCAUX	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
J3	PR45A	2	
M8	PR43D	2	DIFFR_2
L8	PR43C	2	VREF1_2
K4	PR43B	2	
J4	PR43A	2	
M7	PR26D	2	
L7	PR26C	2	
J5	PR26B	2	
H5	PR26A	2	
N9	PR19D	2	
P9	PR19C	2	
G3	PR19B	2	
F3	PR19A	2	
J6	PR18D	2	VREF2_2
H6	PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
D2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
G4	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
F4	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
J7	PR15D	2	
H7	PR15C	2	
G5	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
F5	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
C2	VCCJ	-	
M9	TDO	-	TDO
L9	TMS	-	
D1	TCK	-	
C1	TDI	-	
J8	PROGRAMN	1	
K8	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
B2	CCLK	1	
H9	RESP_URC	-	
H10	VCC12	-	
H8	A_REFCLKN_R	-	
G8	A_REFCLKP_R	-	
C3	VCC12	-	
D3	A_VDDIB0_R	-	
A3	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
B3	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
E5	VCC12	-	
A4	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P38	PL26B	7		PL40B	7	
N35	PL26C	7		PL40C	7	
N36	PL26D	7		PL40D	7	
N39	PL29A	7		PL43A	7	
P39	PL29B	7		PL43B	7	
R34	PL29C	7	VREF1_7	PL43C	7	VREF1_7
T34	PL29D	7	DIFFR_7	PL43D	7	DIFFR_7
L41	PL30A	7		PL44A	7	
M41	PL30B	7		PL44B	7	
W29	PL30C	7		PL44C	7	
Y29	PL30D	7		PL44D	7	
L42	PL31A	7		PL45A	7	
M42	PL31B	7		PL45B	7	
U32	PL31C	7		PL45C	7	
V32	PL31D	7		PL45D	7	
R37	PL33A	7		PL47A	7	
T37	PL33B	7		PL47B	7	
M36	PL33C	7		PL47C	7	
M37	PL33D	7		PL47D	7	
P40	PL34A	7		PL48A	7	
N40	PL34B	7		PL48B	7	
R35	PL34C	7		PL48C	7	
T35	PL34D	7		PL48D	7	
N41	PL35A	7		PL49A	7	
P41	PL35B	7		PL49B	7	
V33	PL35C	7		PL49C	7	
U33	PL35D	7		PL49D	7	
R38	PL37A	7		PL51A	7	
T38	PL37B	7		PL51B	7	
R36	PL37C	7		PL51C	7	
T36	PL37D	7		PL51D	7	
N42	PL38A	7		PL52A	7	
P42	PL38B	7		PL52B	7	
Y31	PL38C	7		PL52C	7	
AA31	PL38D	7		PL52D	7	
U37	PL39A	7		PL53A	7	
V37	PL39B	7		PL53B	7	
U34	PL39C	7		PL53C	7	
V34	PL39D	7		PL53D	7	
U39	PL41A	7		PL55A	7	
T39	PL41B	7		PL55B	7	
V35	PL41C	7		PL55C	7	
W35	PL41D	7		PL55D	7	
R41	PL42A	7		PL56A	7	
T41	PL42B	7		PL56B	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
J1	PR25B	2		PR38B	2	
K1	PR25A	2		PR38A	2	
V12	PR24D	2		PR34D	2	
U12	PR24C	2		PR34C	2	
K2	PR24B	2		PR34B	2	
J2	PR24A	2		PR34A	2	
R10	PR22D	2		PR30D	2	
T10	PR22C	2		PR30C	2	
L5	PR22B	2		PR30B	2	
K5	PR22A	2		PR30A	2	
P9	PR21D	2		PR26D	2	
N9	PR21C	2		PR26C	2	
L6	PR21B	2		PR26B	2	
K6	PR21A	2		PR26A	2	
M8	PR20D	2		PR19D	2	
M9	PR20C	2		PR19C	2	
H1	PR20B	2		PR19B	2	
G1	PR20A	2		PR19A	2	
U14	PR18D	2	VREF2_2	PR18D	2	VREF2_2
T14	PR18C	2		PR18C	2	
H2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
G2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
H3	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
G3	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
R11	PR16D	2		PR15D	2	
P11	PR16C	2		PR15C	2	
J5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
J6	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
P18	VCCJ	-		VCCJ	-	
P19	TDO	-	TDO	TDO	-	TDO
R21	TMS	-		TMS	-	
P20	TCK	-		TCK	-	
P12	TDI	-		TDI	-	
P17	PROGRAMN	1		PROGRAMN	1	
P21	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
P13	CCLK	1		CCLK	1	
H10	RESP_URC	-		RESP_URC	-	
N13	VCC12	-		VCC12	-	
H9	A_REFCLKN_R	-		A_REFCLKN_R	-	
G9	A_REFCLKP_R	-		A_REFCLKP_R	-	
F2	VCC12	-		VCC12	-	
H4	A_VDDIB0_R	-		A_VDDIB0_R	-	
C1	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-6FF1020I[1]	-6	Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-5FF1020I[1]	-5	Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-6FC1152I[2]	-6	Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FC1152I[2]	-5	Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-6FF1152I	-6	Organic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FF1152I	-5	Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-6FC1152I[1]	-6	Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-5FC1152I[1]	-5	Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-6FF1152I	-6	Organic fcBGA	1152	IND	80.1
LFSC3GA80E-5FF1152I	-5	Organic fcBGA	1152	IND	80.1
LFSC3GA80E-6FC1704I[1]	-6	Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-5FC1704I[1]	-5	Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-6FF1704I	-6	Organic fcBGA	1704	IND	80.1
LFSC3GA80E-5FF1704I	-5	Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-6FC1152I[1]	-6	Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FC1152I[1]	-5	Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FF1152I	-6	Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FF1152I	-5	Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FC1704I[1]	-6	Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FC1704I[1]	-5	Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-6FF1704I	-6	Organic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FF1704I	-5	Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FCN1152C[1]	-6	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FCN1152C[1]	-5	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FCN1704C[1]	-6	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FCN1704C[1]	-5	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FFN1704C	-6	Lead-Free Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FFN1704C	-5	Lead-Free Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Date	Version	Section	Change Summary
March 2007 (cont.)	01.5 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Internal Timing Parameters with ispLEVER 6.1 SP1 results.
			Updated t_{FDEL} and t_{CDEL} specifications.
			Updated LatticeSC Family Timing Adders with ispLEVER 6.1 SP1 results.
			Updated PLL specifications to expand frequency range down to 2 MHz and break out jitter for the different ranges.
			Added footnote to sysCLOCK PLL Timing table specifying the conditions for the jitter measurements.
			Added t_{DLL} specification to sysCLOCK DLL Timing table.
			Added footnote to sysCLOCK DLL Timing table specifying the conditions for the jitter measurements.
			Added sysCONFIG Master Parallel Configuration Mode and sysCONFIG SPI Port to LatticeSC sysCONFIG Port Timing table.
		Pin Information	Updated Pin Information Summary with SC40 information.
			Updated LFSC25 Logic Signal Connections: FF1020 with SC40 information.
			Updated LFSC80 Logic Signal Connections: FC1152 with SC40 information.
August 2007	01.6	General	Changed references of "HDC" to "HDC/SI".
			Changed references of "LDCN" to "LDCN/SCS".
			Changed references of "BUSYN/RCLK" to "BUSYN/RCLK/SCK".
			Changed references of "RDCFGN" to "TSALLN".
			Changed references of "TDO/RDDATA" to "TDO".
		Architecture	Updated text in Ripple Mode section.
			Added information to Global Set/Reset.
			Added information for Spread Spectrum Clocking
			Modified information for PLL/DLL Cascading. DLL to PLL is now supported.
			Modified AIL Block text and figure.
			Modified Figure 2-20 DDR/Shift Register Block.
			Added Information to Hot Socketing.
			Added new information for I/O Architecture Rules.
			Added information to SERDES Power Supply Sequencing Requirements.
		DC and Switching Characteristics	Added footnote to Hot Socketing Specifications table.
			Modified Initialization and Standby Supply Current table.
			Modified GSR Timing table.
			Modified sysCLOCK DLL Timing table to include $I_{DUTY.}$
			Deleted Readback Timing information from sysCONFIG Port Timing table.
			Modified data in External Switching Characteristics table.
		Pin Information	Added information to the Signal Descriptions table for HDC/SI, LDCN/SCS.
			Added footnote to Signal Descriptions table.
			Modified Description for signal BUSYN/RCLK/SCK.
			Modified data in Pin Information Summary and device-specific Pinout Information tables.